

# Low voltage PNP power transistor

Datasheet - production data

#### **Features**

- Surface-mounting TO-252 power package in tape and reel
- Complementary to the NPN type MJD31C

### **Application**

 General purpose linear and switching equipment

### **Description**

The device is manufactured in planar technology with "base island" layout. The resulting transistor shows exceptional high gain performance coupled with very low saturation voltage.

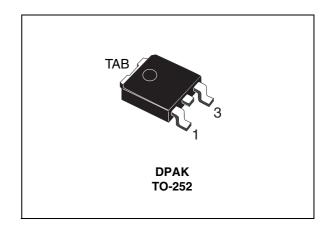


Figure 1. Internal schematic diagram

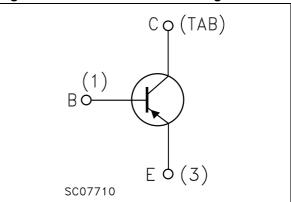


Table 1. Device summary

Order code	Marking	Package	Packaging
MJD32CT4	MJD32C	DPAK	Tape and reel

Electrical ratings MJD32C

# 1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
$V_{CBO}$	Collector-base voltage (I <sub>E</sub> = 0)	-100	V
V <sub>CEO</sub>	Collector-emitter voltage (I <sub>B</sub> = 0)	-100	V
V <sub>EBO</sub>	Emitter-base voltage (I <sub>C</sub> = 0)	-5	V
I <sub>C</sub>	Collector current	-3	Α
I <sub>CM</sub>	Collector peak current	-5	Α
I <sub>B</sub>	Base current	-1	Α
P <sub>TOT</sub>	Total dissipation at T <sub>c</sub> = 25 °C	15	W
T <sub>STG</sub>	Storage temperature	-65 to 150	°C
$T_J$	Max. operating junction temperature	150	°C

Table 3. Thermal data

Symbol	Parameter	Value	Unit
R <sub>thJC</sub>	Thermal resistance junction-case max	8.3	°C/W
R <sub>thJPCB</sub> (1)	Thermal resistance junction-pcb max	50	°C/W

<sup>1.</sup> When mounted on FR-4 board of 1 inch², 2 oz Cu.

## 2 Electrical characteristics

 $T_{case} = 25$  °C unless otherwise specified.

Table 4. Electrical characteristics

Symbol	Parameter	Test con	ditions	Min.	Тур.	Max.	Unit
I <sub>CES</sub>	Collector cut-off current (V <sub>BE</sub> = 0)	V <sub>CE</sub> = - 100 V			-	-20	μΑ
I <sub>CEO</sub>	Collector cut-off current (I <sub>B</sub> = 0)	V <sub>CB</sub> = - 60 V	V <sub>CB</sub> = - 60 V		-	-50	μΑ
I <sub>EBO</sub>	Emitter cut-off current (I <sub>C</sub> = 0)	V <sub>EB</sub> = - 5 V			-	-0.1	mA
V <sub>CEO(sus)</sub> (1)	Collector-emitter sustaining voltage (I <sub>B</sub> = 0)	I <sub>C</sub> = - 30 mA		-100	-		V
V <sub>CE(sat)</sub> (1)	Collector-emitter saturation voltage	I <sub>C</sub> = - 3 A	I <sub>B</sub> = - 375 mA		-	-1.2	<b>V</b>
V <sub>BE(on)</sub> (1)	Base-emitter on voltage	I <sub>C</sub> = - 3 A	V <sub>CE</sub> = - 4 V		-	-1.8	V
h <sub>FE</sub>	DC current gain	I <sub>C</sub> = - 1 A I <sub>C</sub> = - 3 A	V <sub>CE</sub> = - 4 V V <sub>CE</sub> = - 4 V	25 10	-	50	

<sup>1.</sup> Pulse test: pulse duration ≤300 µs, duty cycle ≤2 %

## 2.1 Electrical characteristic (curves)

Figure 2. Safe operating area

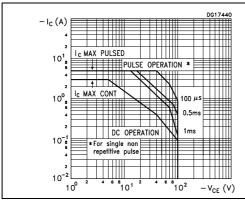
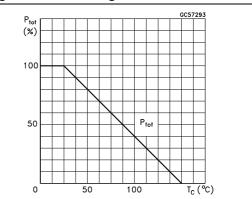


Figure 3. Derating curve



**Electrical characteristics** MJD32C

 $T_J = 150$  °C  $T_J = 150 \,^{\circ}\text{C}$ T<sub>J</sub>=25°C T<sub>J</sub>=25℃ 100 100 V<sub>CE</sub> =−2V V<sub>CE</sub> =-4V 0.01 0.1

Figure 4. Figure 5. DC current gain  $(V_{CE} = -2 V)$ DC current gain (V<sub>CE</sub> = - 4 V)

Figure 6. **Collector-emitter saturation** voltage

10 <u></u> 0.1

- V<sub>CE (sat)</sub> (V)  $h_{\,FE}=\!10$  $T_J = 25$  °C  $T_1 = -40$  °C 0.01 0.01 0.1 - I<sub>C</sub> (A)

Figure 7. **Base-emitter saturation** voltage

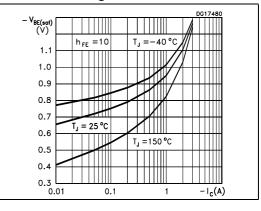
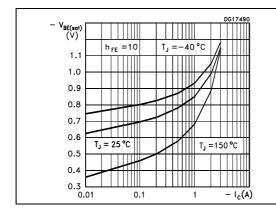
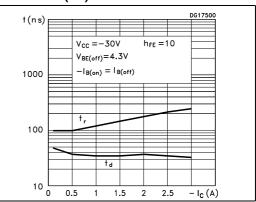


Figure 8. Base-emitter on voltage

Figure 9. Resistive load switching time



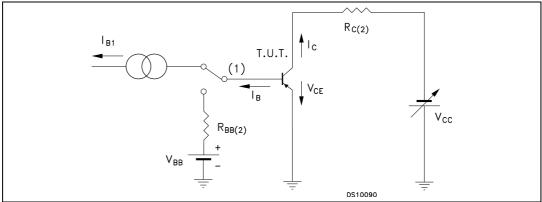


(OTT)  $t(ns) = \frac{0.017510}{V_{CC} = -30V} = \frac{0.017510}{V_{BE(off)} = 4.3V}$   $-l_{B(on)} = l_{B(off)}$   $100 = \frac{1}{10} = \frac{1}{10}$ 

Figure 10. Resistive load switching time (off)

## 2.2 Test circuits

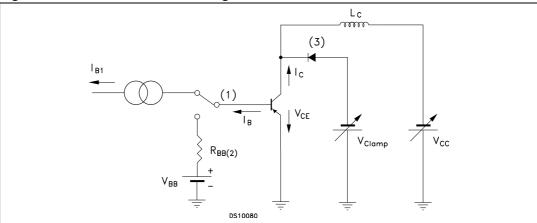
Figure 11. Resistive load switching test circuit



- 1. Fast electronic switch
- 2. Non-inductive resistor

Electrical characteristics MJD32C

Figure 12. Inductive load switching test circuit



- 1. Fast electronic switch
- 2. Non-inductive resistor
- 3. Fast recovery rectifier

# 3 Package mechanical data

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Table 5. DPAK (TO-252) mechanical data

	mm					
Dim.	Min.	Тур.	Max.			
Α	2.20		2.40			
A1	0.90		1.10			
A2	0.03		0.23			
b	0.64		0.90			
b4	5.20		5.40			
С	0.45		0.60			
c2	0.48		0.60			
D	6.00		6.20			
D1		5.10				
Е	6.40		6.60			
E1		4.70				
е		2.28				
e1	4.40		4.60			
Н	9.35		10.10			
L	1		1.50			
L1		2.80				
L2		0.80				
L4	0.60		1			
R		0.20				
V2	0°		8°			

THERMAL PAD

E1

D1

R

GAUGE PLANE

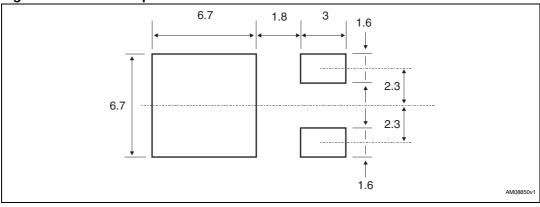
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Figure 13. DPAK (TO-252) drawing

Table 6.	DPAK	(TO-252)	tape	and reel	mechanical	data

Таре				Reel		
Dim.	mm		Dim.	mm		
	Min.	Max.		Min.	Max.	
A0	6.8	7	А		330	
В0	10.4	10.6	В	1.5		
B1		12.1	С	12.8	13.2	
D	1.5	1.6	D	20.2		
D1	1.5		G	16.4	18.4	
Е	1.65	1.85	N	50		
F	7.4	7.6	Т		22.4	
K0	2.55	2.75			•	
P0	3.9	4.1		Base qty.	2500	
P1	7.9	8.1		Bulk qty.	2500	
P2	1.9	2.1				
R	40					
Т	0.25	0.35				
W	15.7	16.3				

Figure 14. DPAK footprint<sup>(a)</sup>



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a. All dimensions are in millimeters

Figure 15. Tape for DPAK (TO-252)

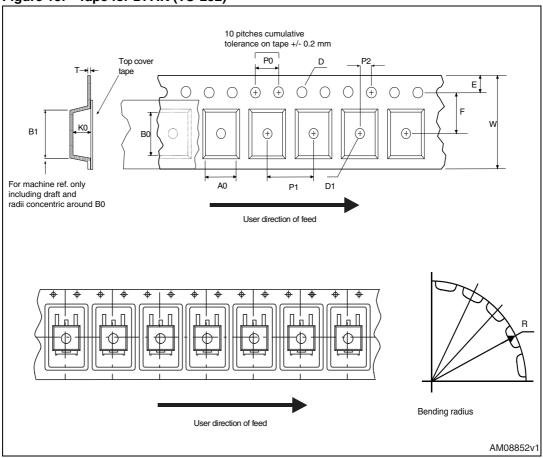
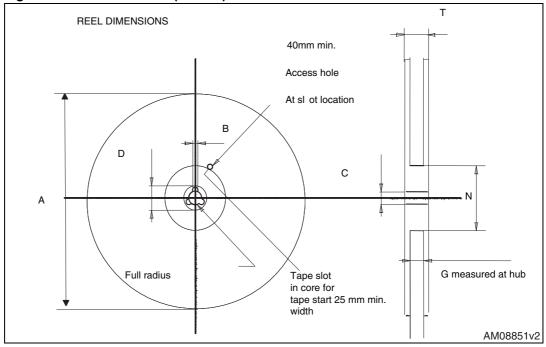


Figure 16. Reel for DPAK (TO-252)



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Revision history MJD32C

# 4 Revision history

Table 7. Document revision history

Date	Revision	Changes
25-Jun-2007	1	Initial release.
09-Nov-2009	2	Updated package mechanical data.
14-Jan-2010	3	Modified Table 3 on page 2.
04-Jun-2012	4	Updated: mechanical data

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